RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

Data sheet

SAW Rx filter
Automotive telematics
WCDMA / LTE band 5; LTE band 26

Series/type: B2601
Ordering code: B39871B2601P810

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Version: 2.0
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1 Application

- Low-loss RX filter for WCDMA & LTE band 5 / LTE band 26 systems
- Usable pass band 35 MHz
- No external matching components required

2 Features

- Package size 1.1±0.1 mm × 0.9±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family (Grade 1: −40 °C to +125 °C)
3 Package

BOTTOM VIEW

0.18 (5x)
0.25 (5x)
0.75

(0.075)

1 2 3

4

5

0.385

0.385

Pad and pitch tolerance ±0.05

SIDE VIEW

A

TOP VIEW

1.1 ±0.1

5 4

1

2 3

16J

SUY

1) Marking for pad number 1
2) Example of encoded lot number
3) Example of encoded filter type number

Land pattern

THRU VIEW

0.23 (5x)

0.25

0.3 (5x)

0.25

0.385 0.385

Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 18).

4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

Please read Cautions and warnings and Important notes at the end of this document.
5 Matching circuit

Figure 3: Schematic of matching circuit. No external matching components required.
## 6 Characteristics

Temperature range for specification \( T_{\text{SPEC}} = -30 \, ^\circ\text{C} \ldots +85 \, ^\circ\text{C} \)

Input terminating impedance \( Z_{\text{IN}} = 50 \, \Omega \)

Output terminating impedance \( Z_{\text{OUT}} = 50 \, \Omega \)

<table>
<thead>
<tr>
<th>Characteristics</th>
<th>min. for ( T_{\text{SPEC}} )</th>
<th>typ. @ +25 (^\circ\text{C})</th>
<th>max. for ( T_{\text{SPEC}} )</th>
</tr>
</thead>
<tbody>
<tr>
<td>Center frequency ( f_c )</td>
<td>—</td>
<td>876.5 MHz</td>
<td>—</td>
</tr>
<tr>
<td></td>
<td>—</td>
<td>881.5 MHz</td>
<td>—</td>
</tr>
<tr>
<td>Maximum insertion attenuation</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>( @ f_{\text{C,806}} )</td>
<td>859... 894 MHz ( \alpha_{\text{max}} )</td>
<td>2.9</td>
<td>3.4</td>
</tr>
<tr>
<td>( @ f_{\text{C,85}} )</td>
<td>869... 894 MHz ( \alpha_{\text{max}} )</td>
<td>2.9</td>
<td>3.4</td>
</tr>
<tr>
<td>( @ f_{\text{carrier}} )</td>
<td>871.4... 891.6 MHz ( \alpha_{\text{WCDMA,max}}^{1)} )</td>
<td>2.4</td>
<td>2.6</td>
</tr>
<tr>
<td>Maximum VSWR</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>( @ \text{input port} )</td>
<td>859... 894 MHz ( \alpha_{\text{VSWR}} )</td>
<td>2.1</td>
<td>2.4</td>
</tr>
<tr>
<td></td>
<td>869... 894 MHz ( \alpha_{\text{VSWR}} )</td>
<td>2.1</td>
<td>2.4</td>
</tr>
<tr>
<td>( @ \text{output port} )</td>
<td>859... 894 MHz ( \alpha_{\text{VSWR}} )</td>
<td>2.2</td>
<td>2.5</td>
</tr>
<tr>
<td></td>
<td>869... 894 MHz ( \alpha_{\text{VSWR}} )</td>
<td>2.2</td>
<td>2.5</td>
</tr>
<tr>
<td>Minimum attenuation</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>( @ f_{\text{carrier}} )</td>
<td>826.4... 846.6 MHz ( \alpha_{\text{WCDMA,min}}^{1)} )</td>
<td>36</td>
<td>39</td>
</tr>
<tr>
<td></td>
<td>840... 849 MHz ( \alpha_{\text{min}} )</td>
<td>31</td>
<td>37</td>
</tr>
<tr>
<td></td>
<td>849... 854 MHz ( \alpha_{\text{min}} )</td>
<td>1.5</td>
<td>10</td>
</tr>
<tr>
<td></td>
<td>909... 930 MHz ( \alpha_{\text{min}} )</td>
<td>14</td>
<td>18</td>
</tr>
<tr>
<td></td>
<td>930... 979 MHz ( \alpha_{\text{min}} )</td>
<td>25</td>
<td>34</td>
</tr>
<tr>
<td></td>
<td>979... 1710 MHz ( \alpha_{\text{min}} )</td>
<td>48</td>
<td>51</td>
</tr>
<tr>
<td></td>
<td>1710... 1785 MHz ( \alpha_{\text{min}} )</td>
<td>46</td>
<td>51</td>
</tr>
<tr>
<td></td>
<td>1710... 1980 MHz ( \alpha_{\text{min}} )</td>
<td>46</td>
<td>50</td>
</tr>
<tr>
<td></td>
<td>1850... 1915 MHz ( \alpha_{\text{min}} )</td>
<td>46</td>
<td>50</td>
</tr>
<tr>
<td></td>
<td>1920... 1980 MHz ( \alpha_{\text{min}} )</td>
<td>46</td>
<td>50</td>
</tr>
<tr>
<td></td>
<td>1980... 2400 MHz ( \alpha_{\text{min}} )</td>
<td>40</td>
<td>47</td>
</tr>
<tr>
<td></td>
<td>2400... 2500 MHz ( \alpha_{\text{min}} )</td>
<td>40</td>
<td>46</td>
</tr>
<tr>
<td></td>
<td>2500... 2577 MHz ( \alpha_{\text{min}} )</td>
<td>40</td>
<td>46</td>
</tr>
<tr>
<td></td>
<td>2577... 2682 MHz ( \alpha_{\text{min}} )</td>
<td>40</td>
<td>45</td>
</tr>
<tr>
<td></td>
<td>2682... 3500 MHz ( \alpha_{\text{min}} )</td>
<td>40</td>
<td>44</td>
</tr>
<tr>
<td></td>
<td>3500... 4900 MHz ( \alpha_{\text{min}} )</td>
<td>35</td>
<td>39</td>
</tr>
<tr>
<td></td>
<td>4900... 5500 MHz ( \alpha_{\text{min}} )</td>
<td>22</td>
<td>30</td>
</tr>
<tr>
<td></td>
<td>5500... 6000 MHz ( \alpha_{\text{min}} )</td>
<td>15</td>
<td>24</td>
</tr>
</tbody>
</table>

\(^{1)}\) Attenuation of WCDMA signal ("power transfer function"). Please refer to definition of Power Transfer Function (PTF) of WCDMA signal (p. 17).

---

Please read **Cautions and warnings** and **Important notes** at the end of this document.
### 7 Maximum ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operable temperature</td>
<td>$T_{OP} = -40 , ^\circ C \ldots +125 , ^\circ C$</td>
</tr>
<tr>
<td>Storage temperature</td>
<td>$T_{STG}^{1)} = -40 , ^\circ C \ldots +125 , ^\circ C$</td>
</tr>
<tr>
<td>DC voltage</td>
<td>$</td>
</tr>
<tr>
<td>Input power @ input port</td>
<td>$P_{IN} = 15 , \text{dBm}$</td>
</tr>
<tr>
<td></td>
<td>Continuous wave for 5000 h @ 55 , ^\circ C.</td>
</tr>
</tbody>
</table>

1) Not valid for packaging material. Storage temperature for packaging material is $-25 \, ^\circ C$ to $+40 \, ^\circ C$.

2) In case of applied DC voltage blocking capacitors are mandatory.
8 Transmission coefficient

Figure 4: Attenuation.
9 Reflection coefficients

**Figure 5:** Reflection coefficient at IN port.

**Figure 6:** Reflection coefficient at OUT port.

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**Please read Cautions and warnings and Important notes at the end of this document.**

May contain US and international export controlled information.
10 Packing material

10.1 Tape

Figure 7: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

<table>
<thead>
<tr>
<th>A_0</th>
<th>1.02±0.05 mm</th>
<th>E_2</th>
<th>6.25 mm (min.)</th>
<th>P_1</th>
<th>2.0±0.1 mm</th>
</tr>
</thead>
<tbody>
<tr>
<td>B_0</td>
<td>1.22±0.05 mm</td>
<td>F</td>
<td>3.5±0.05 mm</td>
<td>P_2</td>
<td>2.0±0.05 mm</td>
</tr>
<tr>
<td>D_0</td>
<td>1.55±0.05 mm</td>
<td>G</td>
<td>–</td>
<td>T</td>
<td>0.25±0.03 mm</td>
</tr>
<tr>
<td>D_1</td>
<td>0.55±0.1 mm</td>
<td>K_0</td>
<td>0.6±0.05 mm</td>
<td>W</td>
<td>8.0–0.9–0.1 mm</td>
</tr>
<tr>
<td>E_1</td>
<td>1.75±0.1 mm</td>
<td>P_0</td>
<td>4.0±0.1 mm</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Table 1: Tape dimensions.
10.2 Reel with diameter of 180 mm

**Figure 8:** Drawing of reel (first-angle projection) with diameter of 180 mm.

**Figure 9:** Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.
Figure 10: Drawing of folding box for reel with diameter of 180 mm.
11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

- **Type number:**
  
  The 4 digit type number of the ordering code, e.g., B3xxxxB1234xxxx, is encoded by a special BASE32 code into a 3 digit marking.

  Example of decoding type number marking on device in decimal code.

  
  \[
  16J \\
  1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 \\
  = 1234
  \]

  The BASE32 code for product type B2601 is 2H9.

- **Lot number:**
  
  The last 5 digits of the lot number, e.g., 12345, are encoded based on a special BASE47 code into a 3 digit marking.

  Example of decoding lot number marking on device in decimal code.

  \[
  5UY \\
  5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 \\
  = 12345
  \]

  Adopted BASE32 code for type number

<table>
<thead>
<tr>
<th>Decimal value</th>
<th>BASE32 code</th>
<th>Decimal value</th>
<th>BASE32 code</th>
</tr>
</thead>
<tbody>
<tr>
<td>0</td>
<td>0</td>
<td>16</td>
<td>G</td>
</tr>
<tr>
<td>1</td>
<td>1</td>
<td>17</td>
<td>H</td>
</tr>
<tr>
<td>2</td>
<td>2</td>
<td>18</td>
<td>J</td>
</tr>
<tr>
<td>3</td>
<td>3</td>
<td>19</td>
<td>K</td>
</tr>
<tr>
<td>4</td>
<td>4</td>
<td>20</td>
<td>M</td>
</tr>
<tr>
<td>5</td>
<td>5</td>
<td>21</td>
<td>N</td>
</tr>
<tr>
<td>6</td>
<td>6</td>
<td>22</td>
<td>P</td>
</tr>
<tr>
<td>7</td>
<td>7</td>
<td>23</td>
<td>Q</td>
</tr>
<tr>
<td>8</td>
<td>8</td>
<td>24</td>
<td>R</td>
</tr>
<tr>
<td>9</td>
<td>9</td>
<td>25</td>
<td>S</td>
</tr>
<tr>
<td>10</td>
<td>A</td>
<td>26</td>
<td>T</td>
</tr>
<tr>
<td>11</td>
<td>B</td>
<td>27</td>
<td>V</td>
</tr>
<tr>
<td>12</td>
<td>C</td>
<td>28</td>
<td>W</td>
</tr>
<tr>
<td>13</td>
<td>D</td>
<td>29</td>
<td>X</td>
</tr>
<tr>
<td>14</td>
<td>E</td>
<td>30</td>
<td>Y</td>
</tr>
<tr>
<td>15</td>
<td>F</td>
<td>31</td>
<td>Z</td>
</tr>
</tbody>
</table>

Table 2: Lists for encoding and decoding of marking.
12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>ramp rate</td>
<td>≤ 3 K/s</td>
</tr>
<tr>
<td>preheat</td>
<td>125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s</td>
</tr>
<tr>
<td>T &gt; 220 °C</td>
<td>30 s to 70 s</td>
</tr>
<tr>
<td>T &gt; 230 °C</td>
<td>min. 10 s</td>
</tr>
<tr>
<td>T &gt; 245 °C</td>
<td>max. 20 s</td>
</tr>
<tr>
<td>T ≥ 255 °C</td>
<td>–</td>
</tr>
<tr>
<td>peak temperature $T_{\text{peak}}$</td>
<td>250 °C +0/-5 °C</td>
</tr>
<tr>
<td>wetting temperature $T_{\text{min}}$</td>
<td>230 °C +5/-0 °C for 10 s ± 1 s</td>
</tr>
<tr>
<td>cooling rate</td>
<td>≤ 3 K/s</td>
</tr>
<tr>
<td>soldering temperature $T$</td>
<td>measured at solder pads</td>
</tr>
</tbody>
</table>

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.
13 ESD protection of SAW filters

SAW filters are Electro Static Discharge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, “ESD matching” has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

In all three figures the shunt inductor $L_{pd}$ could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: “ESD protection for SAW filters”. This report can be found under [www.rf360jv.com/rke](http://www.rf360jv.com/rke). Click on “Applications Notes”.

Figure 12: MLC varistor plus ESD matching.

Figure 13: Suppressor diode plus ESD matching.

Figure 14: 3rd order high-pass structure for basic ESD protection.
14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog [http://www.tdk.co.jp/tefe02/coil.htm#aname1](http://www.tdk.co.jp/tefe02/coil.htm#aname1) and Data Library for circuit simulation [http://www.tdk.co.jp/etvcl/index.htm](http://www.tdk.co.jp/etvcl/index.htm).

14.2 Power Transfer Function (PTF) of WCDMA signal

Attenuation of WCDMA signal, $\alpha_{\text{WCDMA}}$, is defined by

$$\alpha_{\text{WCDMA}}(f_{\text{carrier}}) = 10 \log_{10} \left| \frac{1}{\text{PTF}(f_{\text{carrier}})} \right| \text{dB}$$

and

$$\text{PTF}(f_{\text{carrier}}) = \int_{-\infty}^{+\infty} |S_{21}(f)| H_{\text{RRC}}(f - f_{\text{carrier}}) |^2 df$$

with $f_{\text{carrier}}$ according to 3GPP TS 25.101 (e.g., for the WCDMA B8 pass band, $f_{\text{carrier}}$ ranges from 882.4 MHz to 912.6 MHz which correspond to the lowest and highest TX channels, respectively). $H_{\text{RRC}}(f)$ is the transfer function of the root-raised cosine transmit pulse shaping filter according to 3GPP TS 25.101 using the normalization

$$\int_{-\infty}^{+\infty} |H_{\text{RRC}}(f)|^2 df = 1.$$

14.3 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.4 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.
15  Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data
books, other publications and the website of RF360, or in order-related documents such as shipping
notes, order confirmations and product labels. The varying representations of the ordering codes are
due to different processes employed and do not affect the specifications of the respective products.
Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on
the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal
development and empirical data and illustrated for example purposes, only. As customers' SMD
assembly processes may have a plenty of variants and influence factors which are not under control
or knowledge of RF360, additional careful process development on customer side is necessary and
strongly recommended in order to achieve best soldering results tailored to the particular customer
needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.
16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.

2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.

3. The warnings, cautions and product-specific notes must be observed.

4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.

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